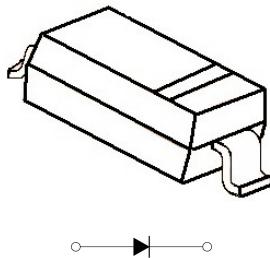


SOD-323**Marking:** 5**SOD-323 Plastic-Encapsulate Schottky Barrier Diode****特征 Features**

- 大电流承受能力。High Current Capability
- 正向压降低。Low Forward Voltage Drop

机械数据 Mechanical Data

- 封装: SOD-323 封装 SOD-323 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	界限 Limit	单位 Unit
峰值反向电压 Peak reverse voltage	V _{RM}	40	V
直流反向电压 DC reverse voltage	V _R	30	V
整流电流 Mean rectifying current	I _o	30	mA
峰值正向浪涌电流 Peak forward surge current 8.3 ms single half sine-wave	I _{FSM}	200	mA
功率消耗 Power Dissipation	P _D	200	mW
结温 Junction Temperature	T _J	125	°C
存储温度 Storage temperature range	T _{STG}	-55~+150	°C

电特性 (TA = 25°C 除非另有规定)

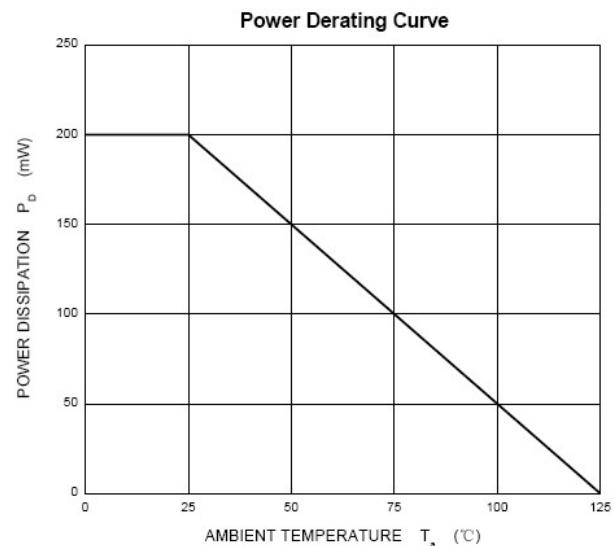
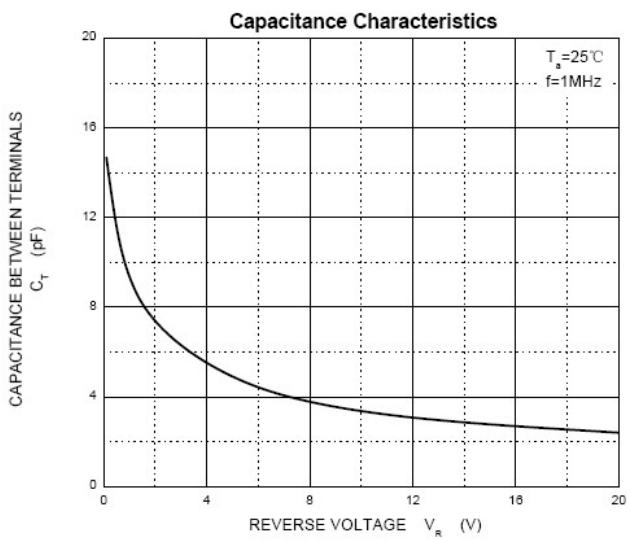
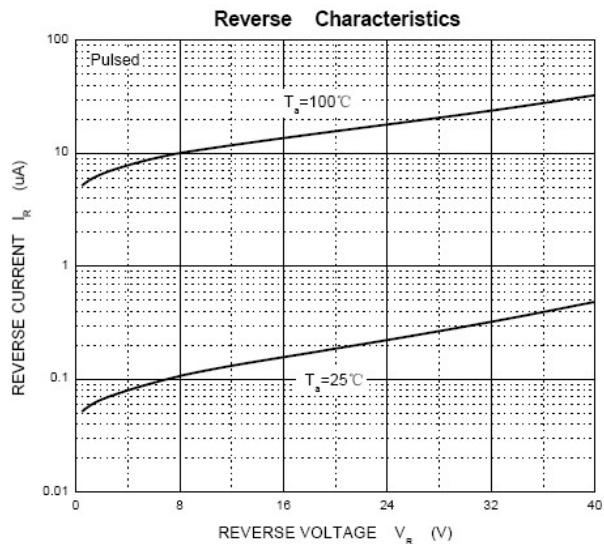
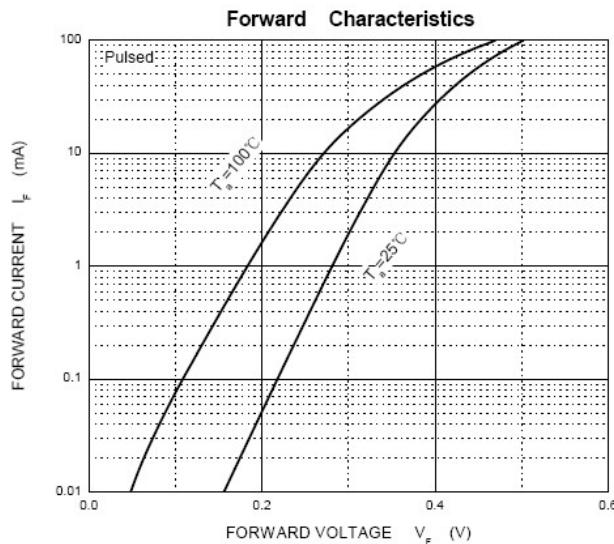
Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

参数 Parameters	符号 Symbol	测试条件 Test conditions	Min.	Typ.	Max.	单位 Unit
最大正向电压 Maximum forward voltage	V _F	I _F = 1.0mA			0.37	V
最大反向电流 Maximum reverse current	I _R	V _R =30V			0.5	uA
结电容 Capacitance between terminals	C _T	V _R =10V, f=1MHz		6		pF

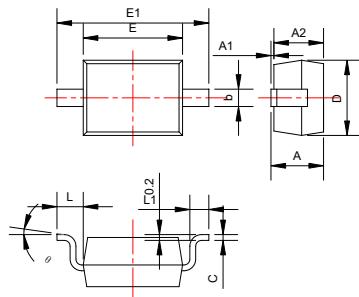


RB751V-40

Typical Characteristics



SOD-323 PACKAGE OUTLINE Plastic surface mounted package



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.000	
A1	0.000	0.100
A2	0.800	0.900
b	0.250	0.350
c	0.080	0.150
D	1.200	1.400
E	1.600	1.800
E1	2.500	2.700
L	0.475REF	
L1	0.250	0.400
θ	0°	8°



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2015-7-11/A